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BERG 2000-0003  
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http://www.patents.ibm.com/cgi-bin/viewpat.cmd/JP07142440A

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(11) Publication number: 07142440 A  
Generated Document.

## PATENT ABSTRACTS OF JAPAN

(21) Application number: 05291013

(51) Int'l. Cl.: H01L 21/304 B08B 7/00

(22) Application date: 19.11.93

(30) Priority:

(43) Date of application publication: 02.06.95

(84) Designated contracting states:

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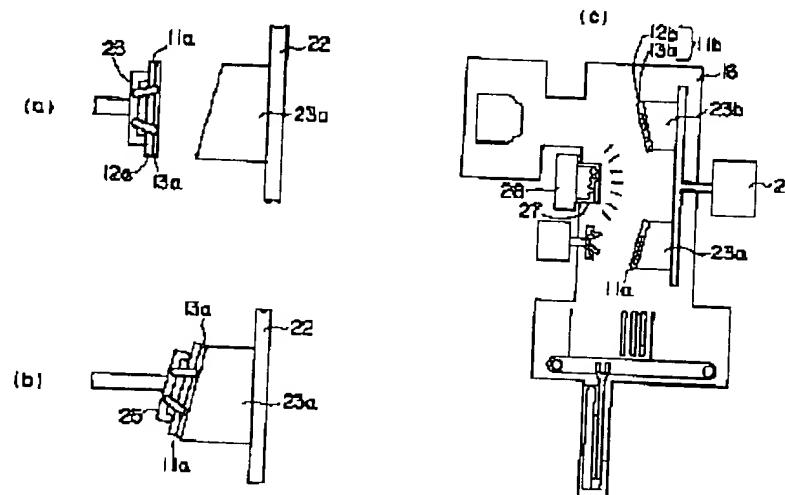
(74) Representative:

### (54) PARTICLE REMOVING METHOD AND SEMICONDUCTOR PRODUCTION SYSTEM HAVING PARTICLE REMOVING MEANS

(57) Abstract:

PURPOSE: To provide a method for removing particles from a semiconductor production system or from the surface of a semiconductor substrate or a reticle more easily and positively with no adverse effect.

CONSTITUTION: Particle eliminators 11a, 11b are bonded, at the adhesive layers 13a, 13b thereof, to bases 23a, 23b for mounting a substrate. Subsequently, the



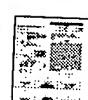
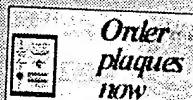
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# P7142440A2: PARTICLE REMOVING METHOD AND SEMICONDUCTOR PRODUCTION SYSTEM HAVING PARTICLE REMOVING MEANS

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Kind:

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Applicant(s):

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Issued/Filed Dates:

June 2, 1995 / Nov. 19, 1993

Application Number:

JP1993000291013

IPC Class:

H01L 21/304; B08B 7/00;

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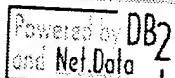
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